




## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	13-07-2023
<b>Company Unique ID</b>	NL 008751171B01		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Material Declaration champion	<b>Representative Title</b>	Material Declaration champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

Uncertainty Statement	
	<p>While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.</p>
Legal Statement	
<b>Supplier Acceptance *</b>	true
	<b>Legal Declaration *</b> <b>Standard</b>
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32MP135DAF7	2A40*501XXXY	A	9991	13-07-2023
	Amount	UoM	Unit type	ST ECOPACK Grade
	370.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	NAC	Copper Alloy	SACN305	

Package Designator	Size	Nbr of instances	Shape	
BGA	11x11	320	bulk solder	
Comment	Package : B0EC TFBGA 11X11 320L PITCH 0.5 MM DM00699790			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-10 Jun 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	2A40*501XXXY				6000000.0	1000000.0				
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	7.106	mg	supplier	die	Silicon (Si)	7440-21-3		6.586	mg	926822	17800				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.058	mg	8162	157				
				supplier	metallization	Copper (Cu)	7440-50-8		0.171	mg	24064	462				
				supplier	metallization	Nickel (Ni)	7440-02-0		0.001	mg	141	3				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.029	mg	4081	78				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.007	mg	985	19				
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	141	3				
				supplier	Passivation	Silicon Nitride	12033-89-5		0.041	mg	5770	111				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.212	mg	29834	573				
				Substrate (A293670)	M-011 Other inorganic materials	106.251	mg	supplier	BT-substrate	Thermosetting resin (Inorganic filler)	Proprietary		8.500	mg	80000	22973
supplier	BT-substrate	Glass cloth	65997-17-3						34.000	mg	320000	91893				
supplier	BT-substrate	Copper foil	7440-50-8						38.250	mg	360000	103379				
supplier	Solder mask	3-methoxy-3-methylbutylacetate	103429-90-9						5.313	mg	50000	14358				
supplier	Solder mask	Morpholinederivative	Trade secret						1.063	mg	10000	2872				
supplier	Solder mask	Barium Sulfate	7727-43-7						12.750	mg	120000	34460				
supplier	Solder mask	Talc containing no as bestiform fibers	14807-96-6						0.531	mg	5000	1436				
supplier	Solder mask	Dipropylene glycol monomethyl ether	34590-94-8						5.844	mg	55000	15794				
DAF (2100AC)	M-011 Other inorganic materials	3.890	mg					supplier	film	Copper (Cu)	7440-50-8		3.059	mg	786250	8286
								supplier	film	Silver (Ag)	7440-22-4		0.204	mg	52500	552
				supplier	film	2,2-dimethyl-1,3-propanediyl bismethacrylate	1985-51-9		0.165	mg	42500	447				
				supplier	film	4-allyl-2,6-bis (2,3-epoxypropyl)phenol; 4-allyl-	Trade secret		0.219	mg	56205	591				
				supplier	film	2-[[[2,2-bis[[[1-oxoallyl]oxy]methyl]butoxy]met	94108-97-1		0.152	mg	39195	412				
				supplier	film	tert-butyl peroxyneodecanoate	26748-41-4		0.088	mg	22500	237				
				supplier	film	Hydroquinone	123-31-9		0.003	mg	850	9				
				Bonding wire (CuPd)	Precious metals	2.181	mg	supplier	Bonding wire	Copper (Cu)	7440-50-8		2.106	mg	965500	5691
supplier	Bonding wire	Palladium (Pd)	7440-05-3						0.068	mg	31000	183				
supplier	Bonding wire	Gold (Au)	78440-57-5						0.008	mg	3500	21				
Encapsulation (KE-G1250AAS)	M-011 Other inorganic materials	224.309	mg	supplier	Molding Compound	Epoxy resin	Trade secret		8.972	mg	40000	24250				
				supplier	Molding Compound	Silica(Fused)	60676-86-0,7631-86-9		204.121	mg	910000	551679				
				supplier	Molding Compound	Phenol resin	Trade secret		10.318	mg	46000	27887				
Solderballs (SACN305)	Solder	26.263	mg	supplier	Molding Compound	Carbon Black	1333-86-4		0.897	mg	4000	2425				
				supplier	Solder	Metallic Tin	7440-31-5		25.331	mg	964500	68461				
				supplier	Solder	Silver Atom	7440-22-4		0.788	mg	30000	2129				
				supplier	Solder	Metallic Copper	7440-50-8		0.131	mg	5000	355				
supplier	Solder	Nickel Element	7440-02-2		0.013	mg	500	35								